

Fig. 1  
PRIOR ART

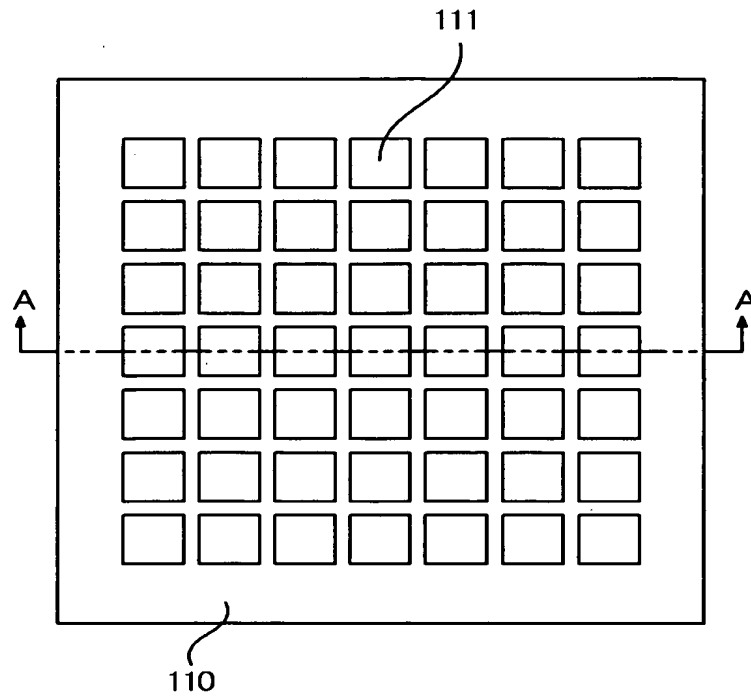


Fig. 3

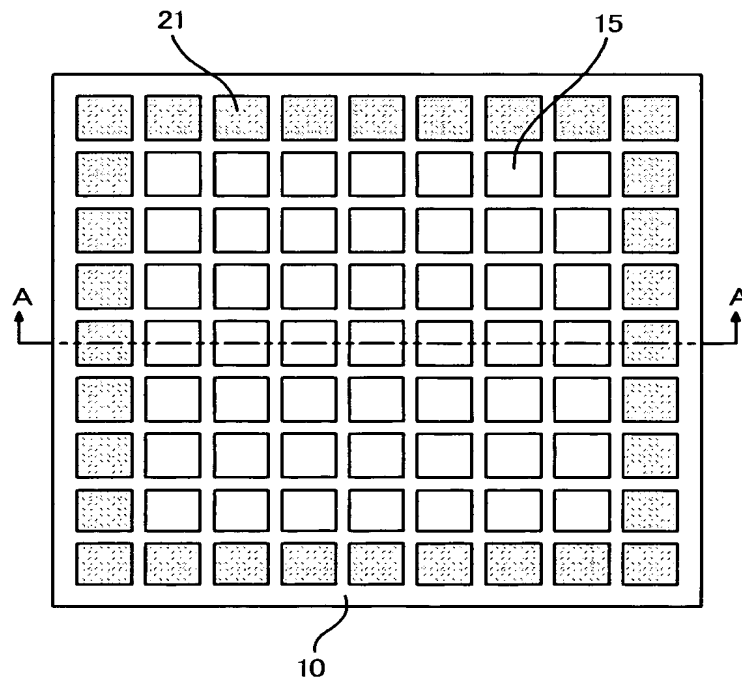


Fig. 2 PRIOR ART

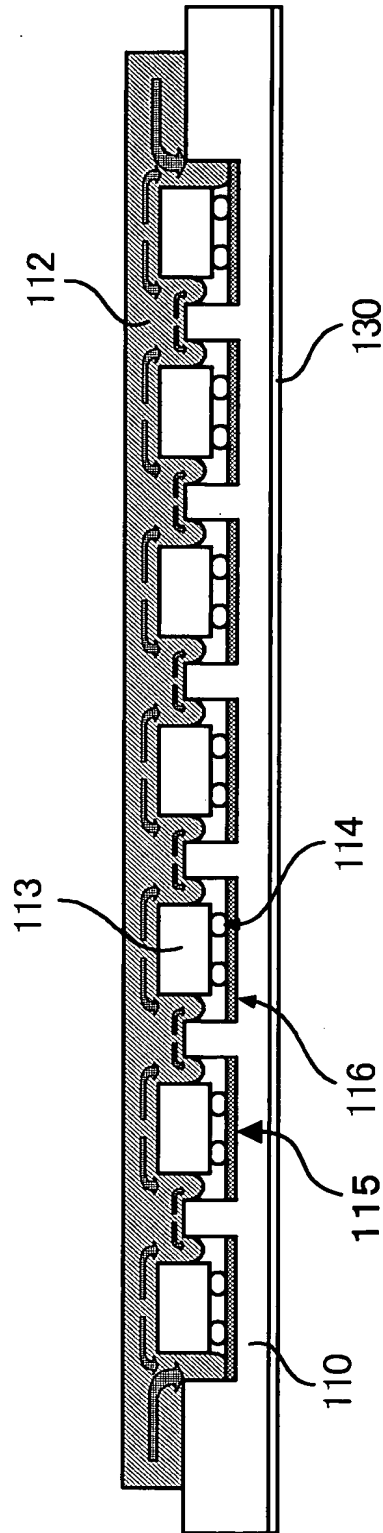


Fig. 4A

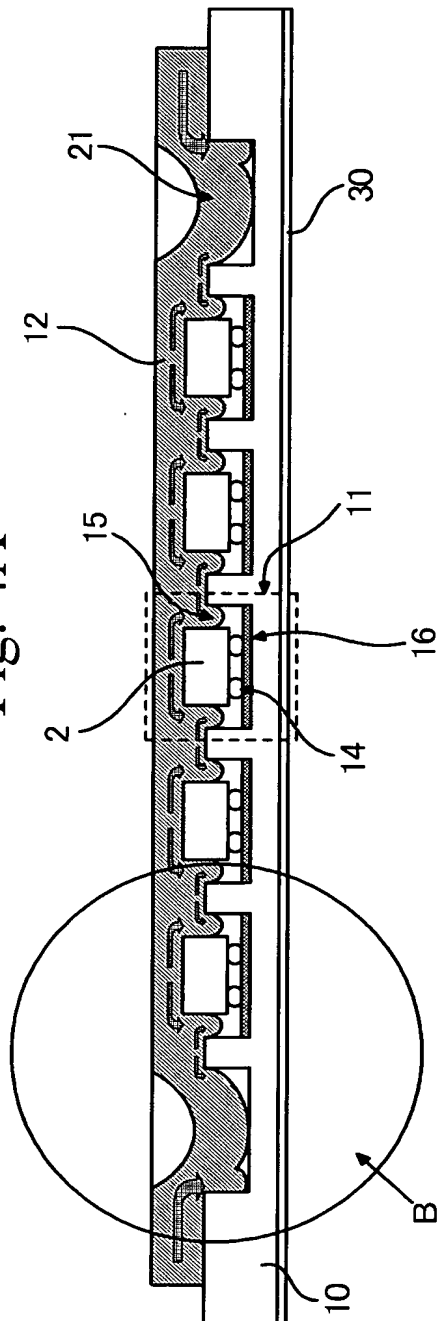


Fig. 4B

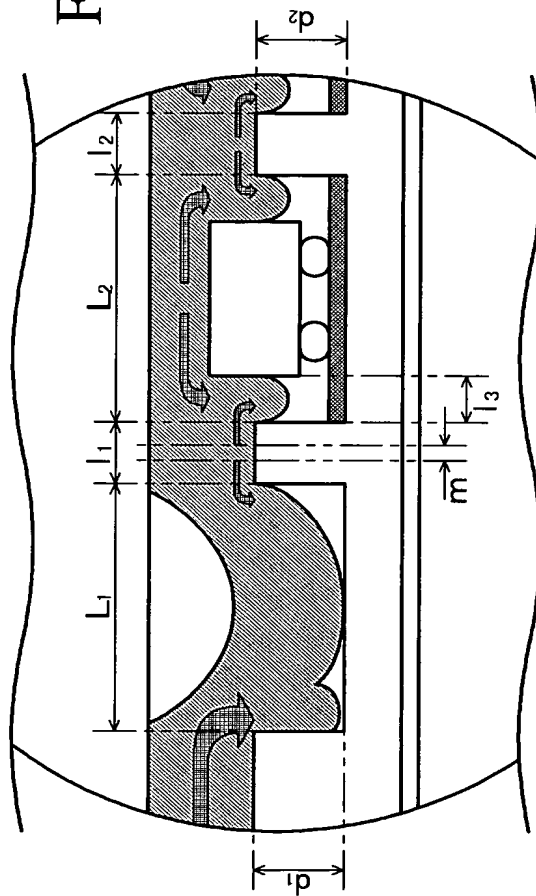


Fig. 5A



Fig. 5B



Fig. 5C

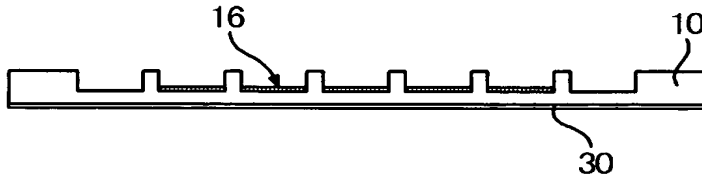


Fig. 5D

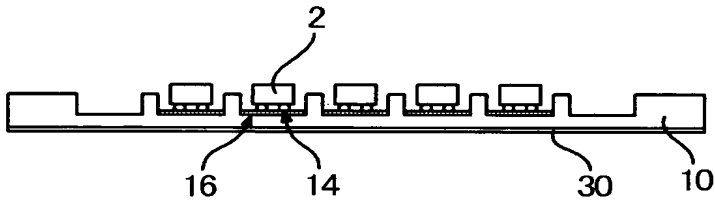


Fig. 5E

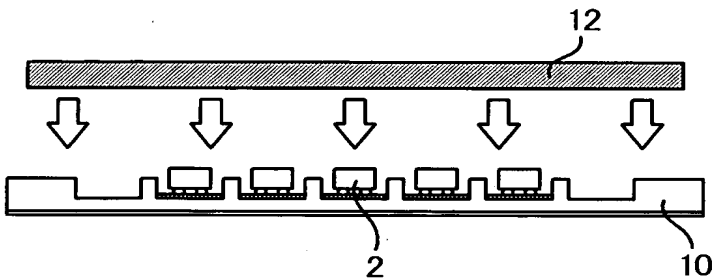


Fig. 5F

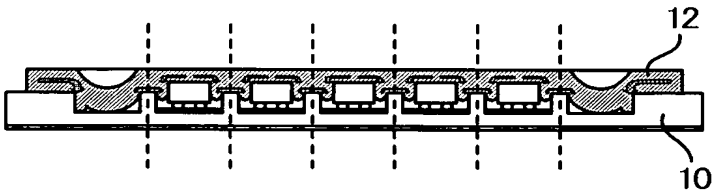
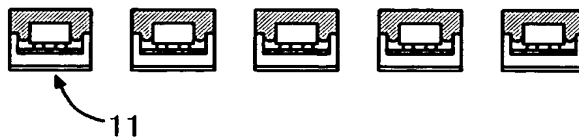
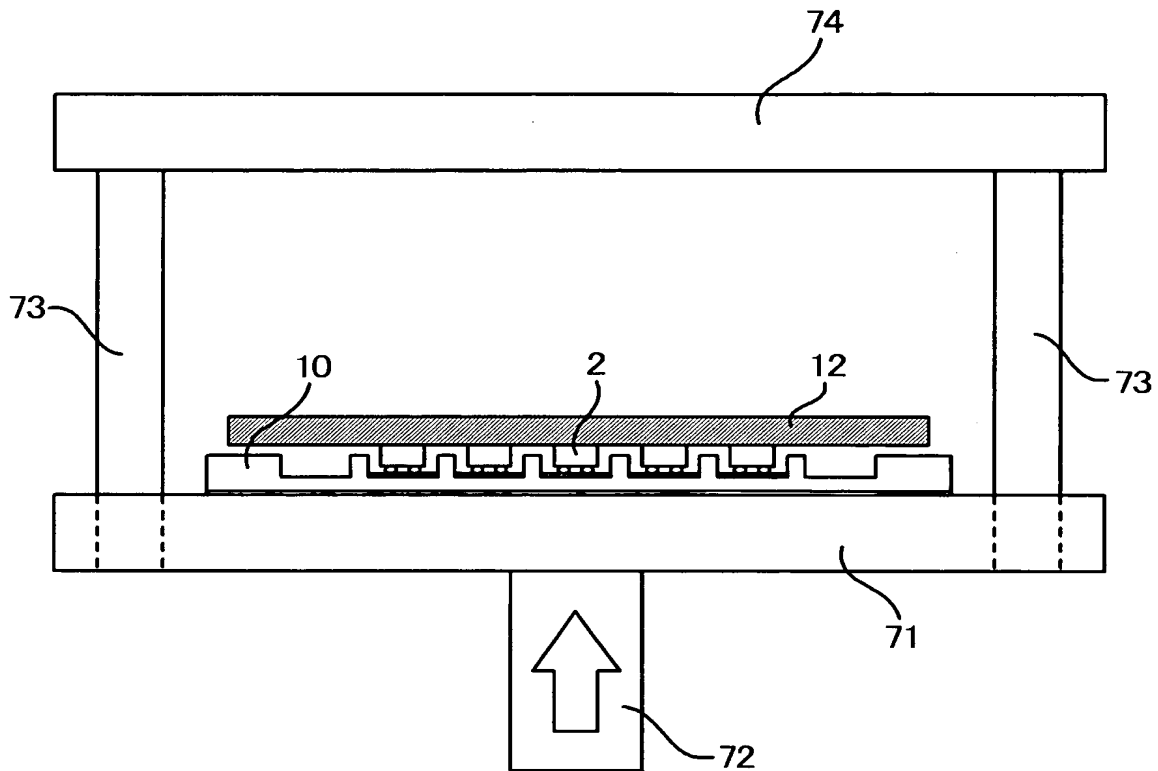


Fig. 5G



Title: METHOD OF FABRICATING  
ELECTRONIC PARTS PACKAGED WITH  
RESIN AND BASEBOARD USED FOR THE  
METHOD  
Inventor: Shingo MASUKO  
Appln. No.: Unknown  
Docket No.: 025720-00023

Fig. 6



Title: METHOD OF FABRICATING  
ELECTRONIC PARTS PACKAGED WITH  
RESIN AND BASEBOARD USED FOR THE  
METHOD  
Inventor: Shingo MASUKO  
Appln. No.: Unknown  
Docket No.: 025720-00023

Fig. 7

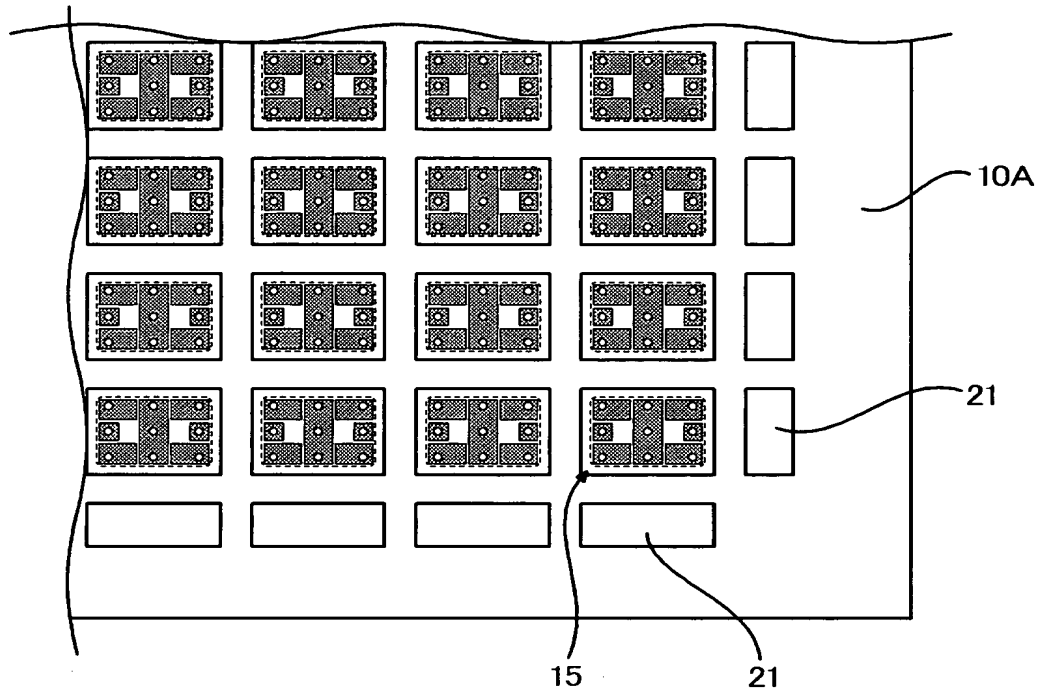
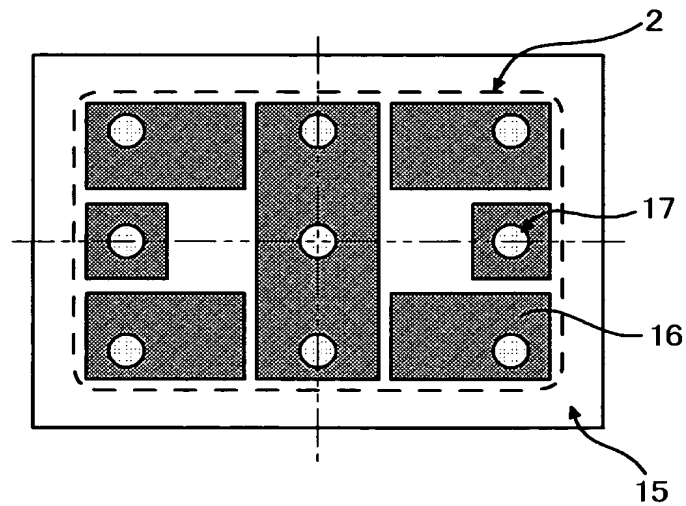


Fig. 8



Title: METHOD OF FABRICATING  
ELECTRONIC PARTS PACKAGED WITH  
RESIN AND BASEBOARD USED FOR THE  
METHOD

Inventor: Shingo MASUKO

Appln. No.: Unknown

Docket No.: 025720-00023

Fig. 9

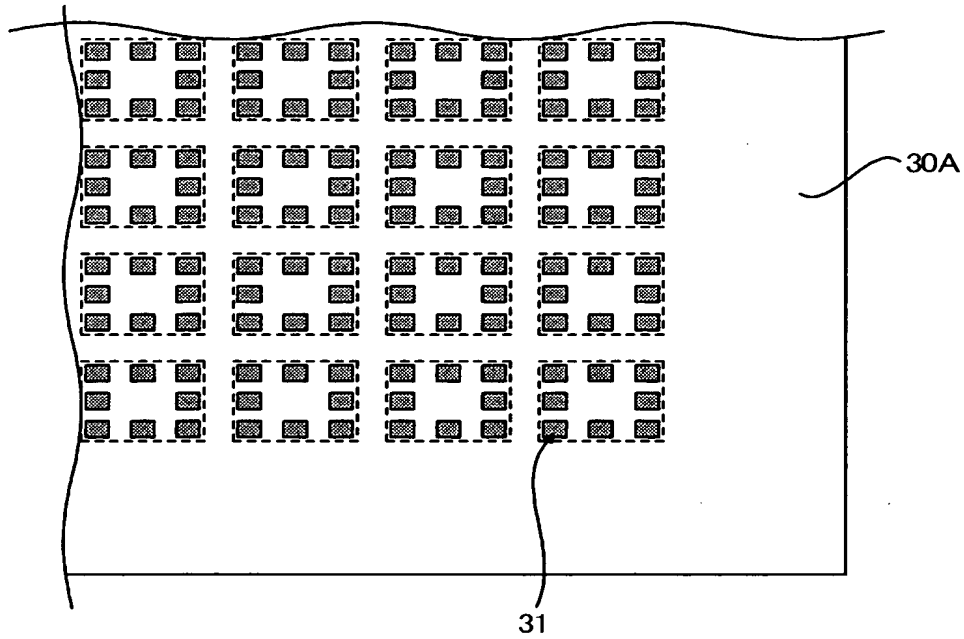
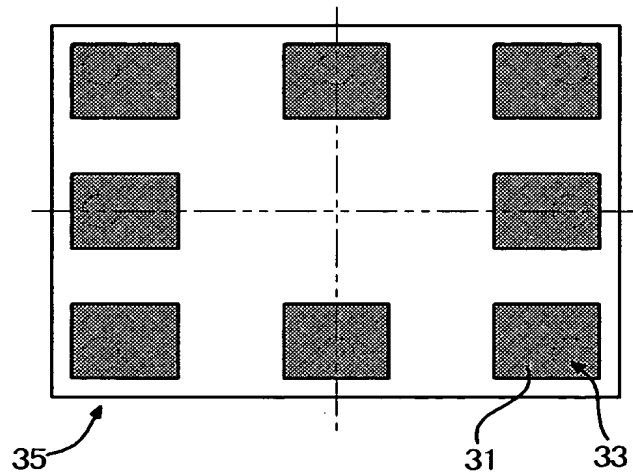


Fig. 10



Title: METHOD OF FABRICATING  
ELECTRONIC PARTS PACKAGED WITH  
RESIN AND BASEBOARD USED FOR THE  
METHOD  
Inventor: Shingo MASUKO  
Appln. No.: Unknown  
Docket No.: 025720-00023

Fig. 11

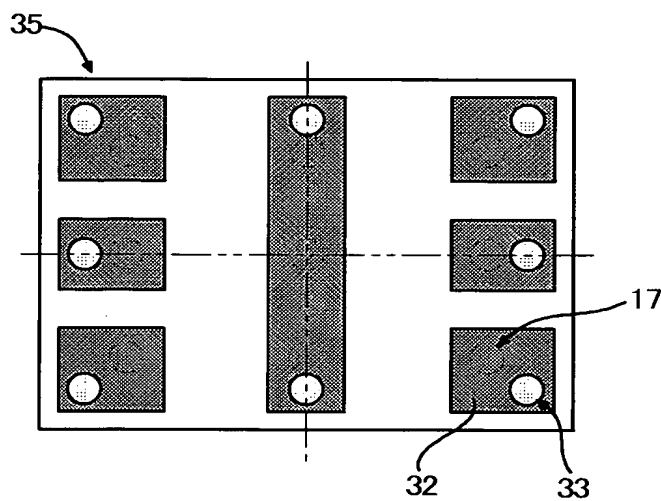


Fig. 12

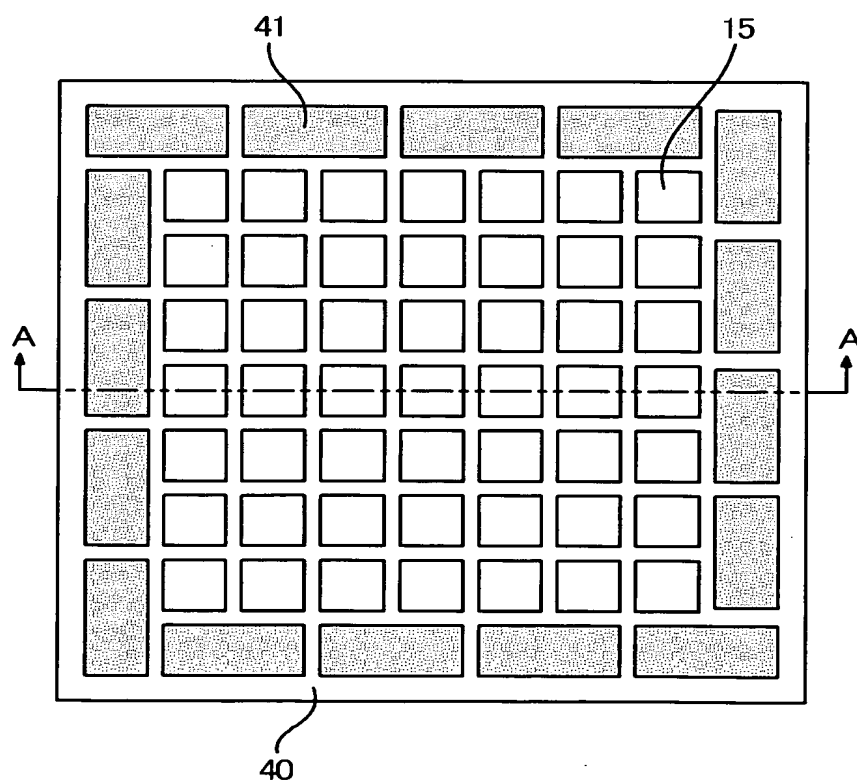




Fig. 13

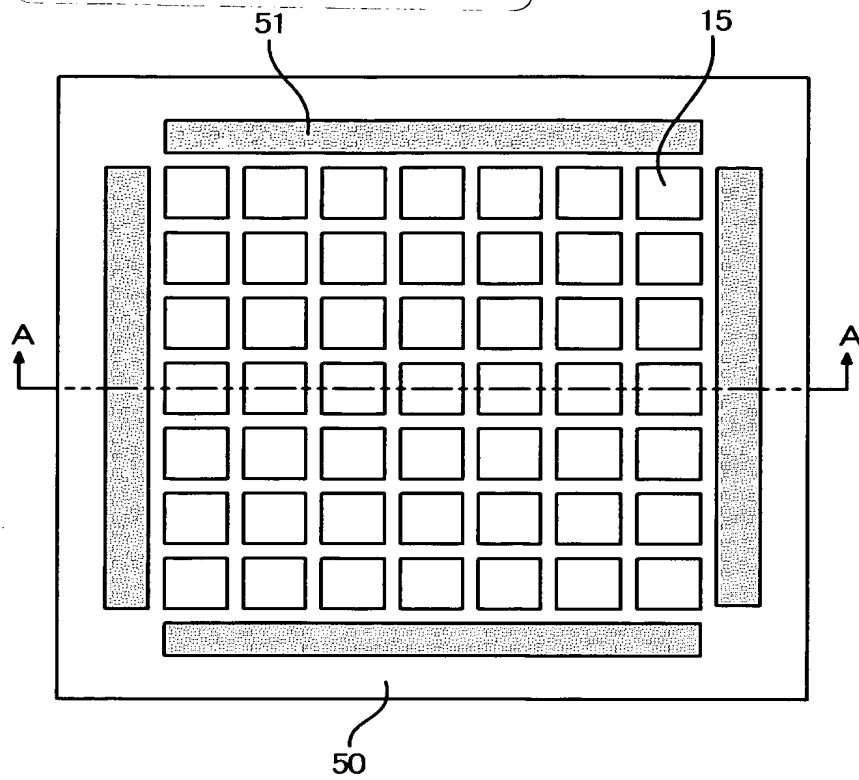


Fig. 14

